- **Controlled Baseline**
  - **One Assembly/Test Site, One Fabrication Site**
- **Extended Temperature Performance of −55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product Change Notification**
- **Qualification Pedigree[†]**
- **Optimized for Off-line and DC-to-DC Converters**
- **Low Start Up Current (<0.5 mA)**
- **Trimmed Oscillator Discharge Current**

- **Automatic Feed Forward Compensation**
- **Pulse-by-Pulse Current Limiting**
- **Enhanced Load Response Characteristics**
- **Under-Voltage Lockout With Hysteresis**
- **Double Pulse Suppression**
- **High Current Totem Pole Output**
- **Internally Trimmed Bandgap Reference**
- **500 kHz Operation**
- **Low R_O Error Amp**

[†] Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

D PACKAGE
(TOP VIEW)

COMP	1	8	V_{REF}
V_{FB}	2	7	V_{CC}
I_{SENSE}	3	6	OUTPUT
R_T/C_T	4	5	GND
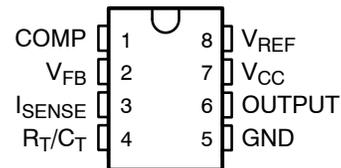
description

The UC1842A/3A/4A/5A family of control ICs is a pin-for-pin compatible improved version of the UC3842/3/4/5 family. Providing the necessary features to control current mode switched mode power supplies, this family has the following improved features. Start up current is guaranteed to be less than 0.5 mA. Oscillator discharge is trimmed to 8.3 mA. During under voltage lockout, the output stage can sink at least 10 mA at less than 1.2 V for V_{CC} over 5 V.

The difference between members of this family are shown in the table below.

PART NUMBER	UVLO ON	UVLO OFF	MAXIMUM DUTY CYCLE
UC1842A	16 V	10 V	<100%
UC1843A	8.5 V	7.9 V	<100%
UC1844A	16 V	10 V	<50%
UC1845A	8.5 V	7.9 V	<50%

ORDERING INFORMATION[‡]

T_A	PACKAGE[‡]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−55°C to 125°C	SOP – D	Tape and reel	UC1842AMDREP	1842AME
−55°C to 125°C	SOP – D	Tape and reel	UC1843AMDREP	1843AME
−55°C to 125°C	SOP – D	Tape and reel	UC1844AMDREP	1844AME
−55°C to 125°C	SOP – D	Tape and reel	UC1845AMDREP	1845AME

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TEXAS INSTRUMENTS

block diagram
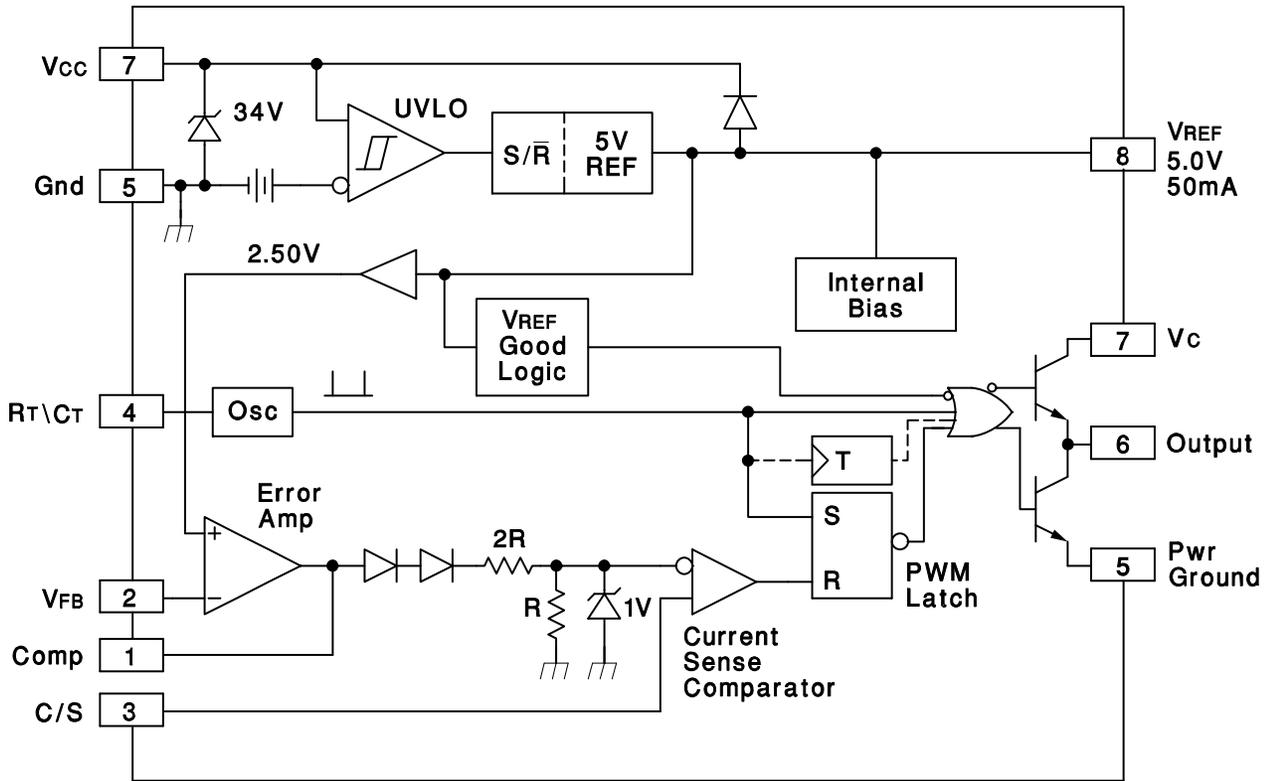
NOTES: 1. Toggle flip flop used only in 1844A and 1845A.

Ordering Information
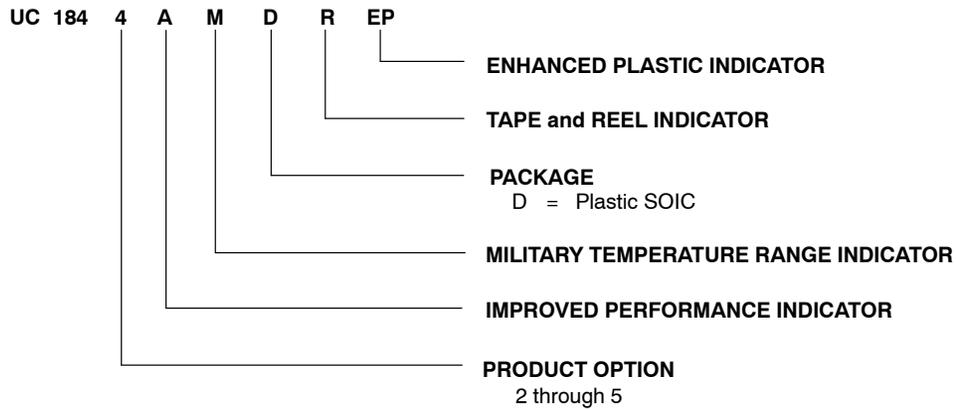

```
UC  184  4  A  M  D  R  EP
```

ENHANCED PLASTIC INDICATOR

TAPE and REEL INDICATOR

PACKAGE
  D = Plastic SOIC

MILITARY TEMPERATURE RANGE INDICATOR

IMPROVED PERFORMANCE INDICATOR

PRODUCT OPTION
  2 through 5

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†‡

V_{CC} voltage (low impedance source)	30 V
V_{CC} voltage (I_{CC} mA)	self limiting
Output current, I_O	±1 A
Output energy (capacitive load)	5 µJ
Analog Inputs (pins 2, 3)	–0.3 V to 6.3 V
Error Amp Output Sink current	10 mA
Power Dissipation at T_A < 25°C	1 W
Package thermal impedance, θ_{JA} (see Note 1):	97°C/W
Storage temperature range, T_{stg}	–65°C to 150°C
Maximum junction temperature, T_J	150°C
Lead temperature soldering 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and
  functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not
  implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

‡ Unless otherwise indicated, voltages are reference to ground and currents are positive into and negative out of the specified terminals.

NOTE 1:   Long term high-temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction
           of overall device life. See http://www.ti.com/ep_quality for additional information on enhanced plastic packaging.

electrical characteristics, T_A = –55°C to 125°C for the UC184xAM-EP, V_{CC} = 15 V (see Note 1), R_T = 10 kΩ, C_T = 3.3 nF, and T_A = T_J (unless otherwise stated)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNITS
Reference Section						
Output voltage	T_J = 25°C, I_O = 1 mA		4.95	5	5.05	V
Line regulation voltage	V_{IN} = 12 V to 25 V			6	20	mV
Load regulation voltage	I_O = 1 mA to 20 mA			6	25	mV
Temperature stability	See Notes NO TAG and NO TAG			0.2	0.4	mV/°C
Total output variation voltage	Line, Load, Temp.		4.9		5.1	V
Output noise voltage	f = 10 Hz to 10 kHz, See Note NO TAG	T_J = 25°C		50		µV
Long term stability	1000 hours, See Note 2	T_A = 125°C		5	25	mV
Output short-circuit current			–30	–100	–180	mA
Oscillator Section						
Initial accuracy	See Note NO TAG	T_J = 25°C	47	52	57	kHz
Voltage stability	V_{CC} = 12 V to 25 V			0.2%	1%	
Temperature stability	T_A = MIN to MAX, See Note 2			5%		
Amplitude peak-to-peak	V pin 4, See Note 2			1.7		V
Discharge current	V pin 4 = 2 V, See Note 3	T_J = 25°C	7.8	8.3	8.8	mA
		T_J = Full range	7.5		8.8	

NOTES: 1.   Adjust V_{CC} above the start threshold before setting at 15 V.
         2.   Not production tested.
         3.   This parameter is measured with R_T = 10 kΩ to V_{REF}. This contributes approximately 300 µA of current to the measurement. The
              total current flowing into the $R_{T/C}$ pin will be approximately 300 µA higher than the measured value.

![Texas Instruments logo]

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electrical characteristics, T_A = −55°C to 125°C for the UC184xAM-EP, V_{CC} = 15 V (see Note 1), R_T = 10 kΩ, C_T = 3.3 nF, and T_A = T_J (unless otherwise stated)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNITS
Error Amplifier Section						
Input voltage	COMP = 2.5 V		2.45	2.5	2.55	V
Input bias current				−0.3	−1	µA
Open loop voltage gain (A_{VOL})	V_O = 2 V to 4 V		65	90		dB
Unity gain bandwidth	See Note 2	T_J = 25°C	0.7	1		MHz
PSRR	V_{CC} = 12 V to 25 V		60	70		dB
Output sink current	FB = 2.7 V, COMP = 1.1 V		2	6		mA
Output source current	FB = 2.3 V, COMP = 5 V		−0.5	−0.8		mA
V_{OUT} high	FB = 2.3 V, R_L = 15 kΩ to GND		5	6		V
V_{OUT} low	FB = 2.7 V, R_L = 15 kΩ to V_{REF}			0.7	1.1	V
Current Sense Section						
Gain	See Note 3 and Note 4		2.85	3	3.15	V/V
Maximum input signal	COMP = 5 V, See Note 3		0.9	1	1.1	V
PSRR	V_{CC} = 12 V to 25 V, See Note 3			70		dB
Input bias current				−2	−10	µA
Delay to output	I_{SENSE} = 0 V to 2 V, See Note 2			150	300	ns
Output Section (OUT)						
Low-level output voltage	I_{OUT} = 20 mA			0.1	0.4	V
	I_{OUT} = 200 mA			15	2.2	
High-level output voltage	I_{OUT} = −20 mA		13	13.5		V
	I_{OUT} = −200 mA		12	13.5		
Rise time	C_L = 1 nF, See Note 2	T_J = 25°C		50	150	ns
Fall time	C_L = 1 nF, See Note 2	T_J = 25°C		50	150	ns
UVLO saturation	V_{CC} = 5 V, I_{OUT} = 10 mA			0.7	1.2	V
Undervoltage Lockout Section						
Start threshold		UC1842A, UC1844A	15	16	17	V
		UC1843A, UC1845A	7.8	8.4	9	
Minimum operation voltage after turn on		UC1842A, UC1844A	9	10	11	V
		UC1843A, UC1845A	7	7.6	8.2	

NOTES: 1. Adjust V_{CC} above the start threshold before setting at 15 V.
2. Not production tested.
3. Parameter measured at trip point of latch with V_{FB} at 0 V.
4. Gain is defined by: $A = \dfrac{\Delta V_{COMP}}{\Delta V_{SENSE}}$; $0 \leq V_{SENSE} \leq 0.8$ V.

electrical characteristics, T_A = −55°C to 125°C for the UC184xAM-EP, V_{CC} = 15 V (see Note 1), R_T = 10 kΩ, C_T = 3.3 nF, and T_A = T_J (unless otherwise stated)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNITS
PWM Section						
Maximum duty cycle		UC1842A, UC1843A	94%	96%	100%	
		UC1844A, UC1845A	47%	48%	50%	
Minimum duty cycle					0%	
Total Standby Current						
Start-up current				0.3	0.5	mA
Operating supply current	FB = 0 V, SENSE = 0 V			11	17	mA
V_{CC} internal zener voltage	I_{CC} = 25 mA		30	34		V

NOTES: 1. Adjust V_{CC} above the start threshold before setting at 15 V.

PARAMETER MEASUREMENT INFORMATION
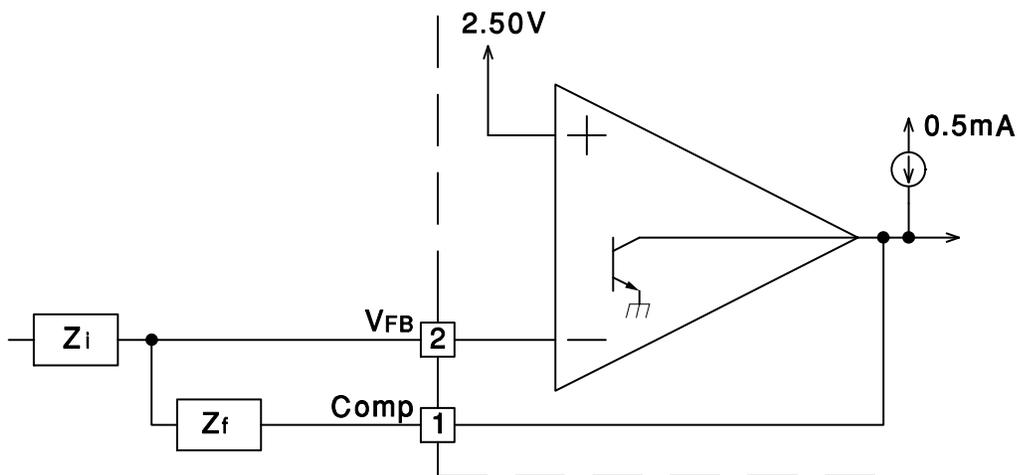
Error Amp can source and sink up to 0.5 mA and sink up to 2 mA.

Figure 1. Error Amp Configuration

PARAMETER MEASUREMENT INFORMATION

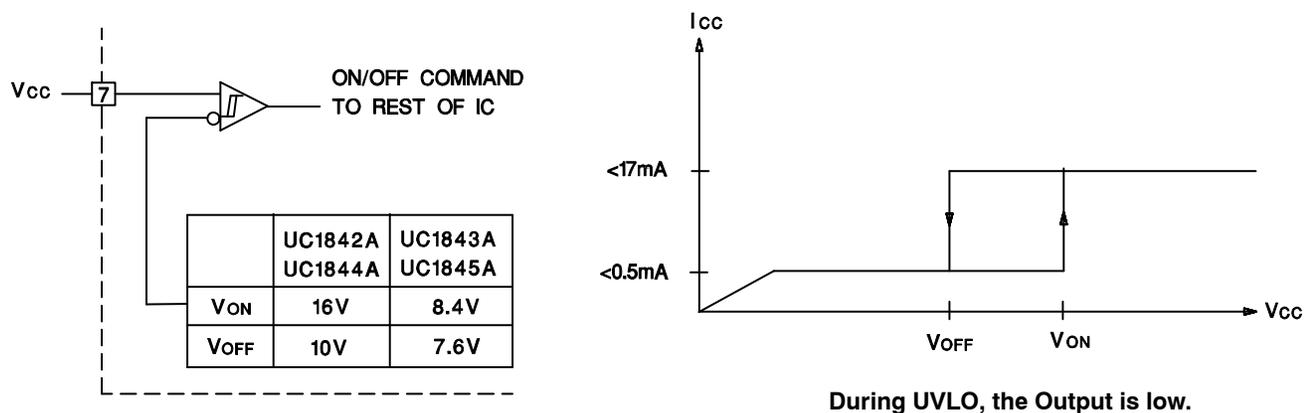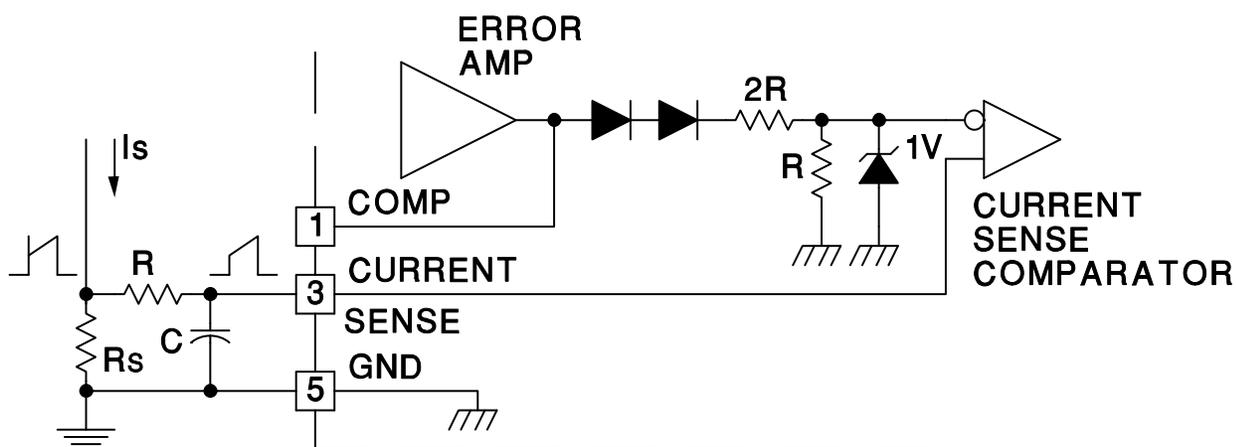|	UC1842A UC1844A	UC1843A UC1845A
V_{ON}	16V	8.4V
V_{OFF}	10V	7.6V

During UVLO, the Output is low.

Figure 2. Under Voltage Lockout

Peak Current (Is) is determined by the following formula:

$$Ismax' \frac{1V}{RS}$$

A small RC filter may be required to suppress switch transients.
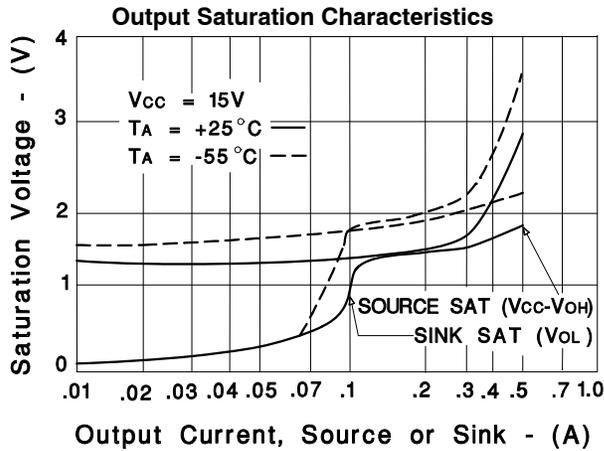
Figure 3. Current Sense Circuit

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PARAMETER MEASUREMENT INFORMATION

Output Saturation Characteristics

V_{CC} = 15V
T_A = +25°C ——
T_A = -55°C - - - -

SOURCE SAT (V_{CC}-V_{OH})
SINK SAT (V_{OL})

Output Current, Source or Sink - (A)

Figure 4

Error Amplifier Open-Loop Frequency Response

Av
ϕ

Frequency - (Hz)
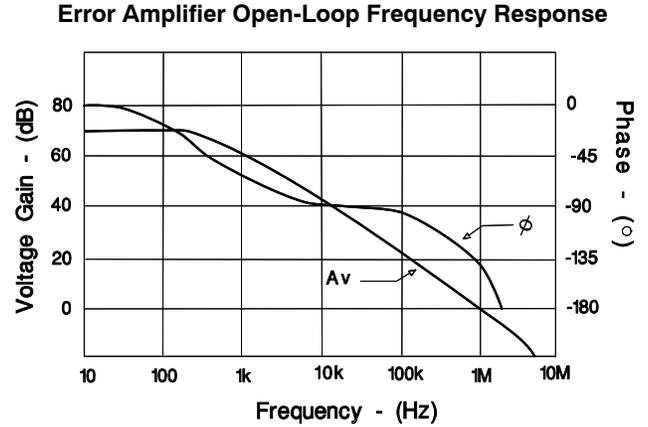
Figure 5

APPLICATION INFORMATION
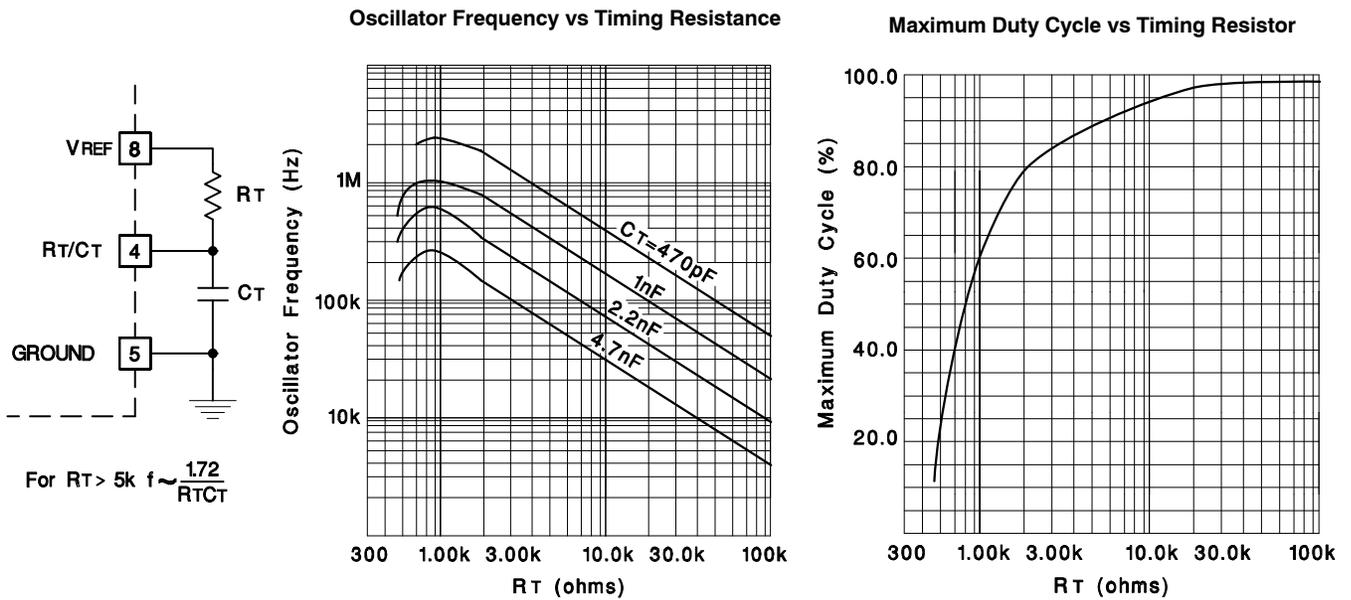
Oscillator Frequency vs Timing Resistance

C_T=470pF
1nF
2.2nF
4.7nF

R_T (ohms)

VREF [8]
RT/CT [4]
GROUND [5]

R_T
C_T

For R_T > 5k $f \sim \dfrac{1.72}{R_T C_T}$

Maximum Duty Cycle vs Timing Resistor

R_T (ohms)

Figure 6. Oscillator

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APPLICATION INFORMATION
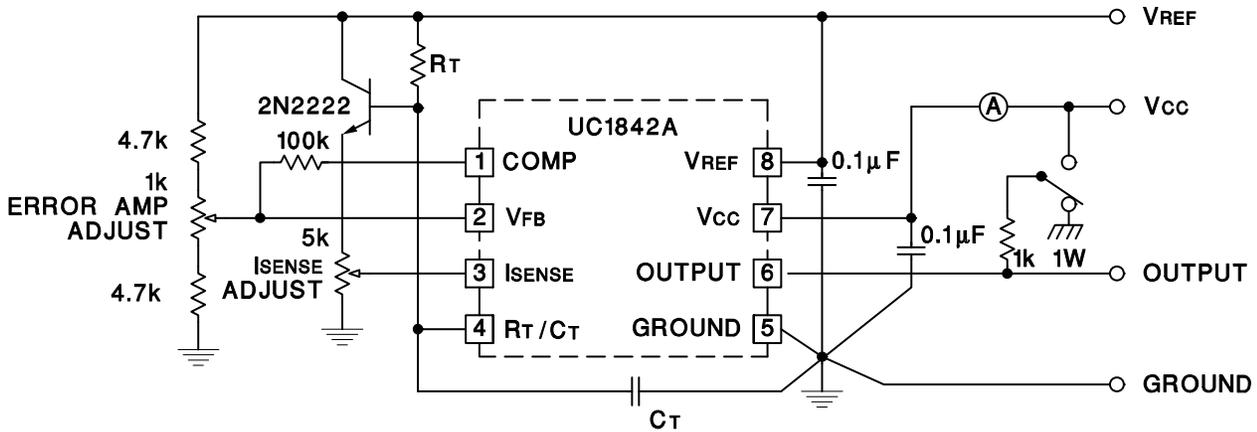
High peak currents associated with capacitive loads necessitate careful grounding techniques. Timing and bypass capacitors should be connected close to pin 5 in a single point ground. The transistor and 5k potentiometer are used to sample the oscillator waveform and apply an adjustable ramp to pin 3.

**Figure 7. Open-Loop Laboratory Text Fixture**
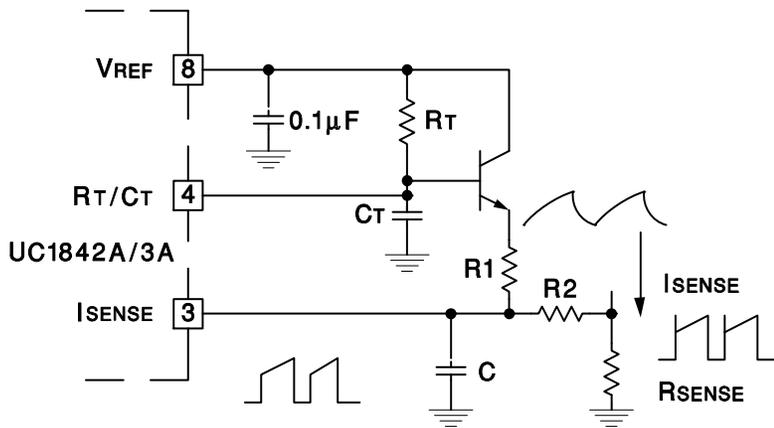
A fraction of the oscillator ramp can be resistively summed with the current sense signal to provide slope compensation for converters requiring duty cycles over 50%.
Note that capacitor, C, forms a filter with R2 to suppress the leading edge switch spikes.

Figure 8. Slope Compression

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APPLICATION INFORMATION
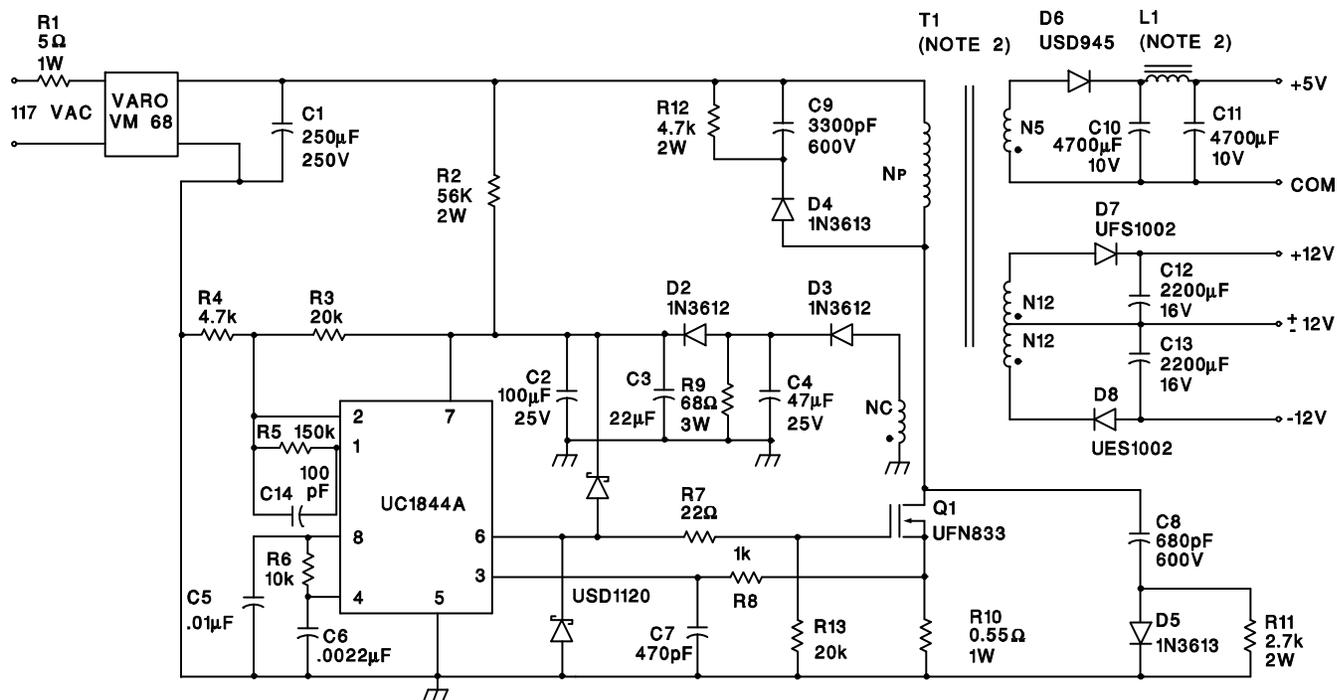
Power Supply Specifications

1. Input Voltage   95VAC to 130VAC (50 Hz/60 Hz)
2. Line Isolation   3750 V
3. Switching Frequency 40 kHz
4. Efficiency, Full Load 70%
5. Output Voltage:
   A. +5V, ±5%; 1A to 4A Load
   B. +12V, ±3%; 0.1A to 0.3A Load Ripple voltage: 100 mV P-P Max
   C. −12V, ±3%; 0.1A to 0.3A Load Ripple voltage: 100 mV P-P Max

Figure 9. Off-Line Flyback Regulator

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
UC1842AMDREP	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	1842AME
UC1842AMDREP.A	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	1842AME
UC1843AMDREP	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	1843AME
UC1843AMDREP.A	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	1843AME
UC1844AMDREP	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	1844AME
UC1844AMDREP.A	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	1844AME
UC1845AMDREP	NRND	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	(1845AE, 1845AME)
UC1845AMDREP.A	NRND	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	(1845AE, 1845AME)
UC1845AMDREPG4	NRND	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	(1845AE, 1845AME)
V62/03625-01YE	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	1842AME
V62/03625-02YE	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	1843AME
V62/03625-03YE	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	1844AME
V62/03625-04YE	NRND	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	(1845AE, 1845AME)

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
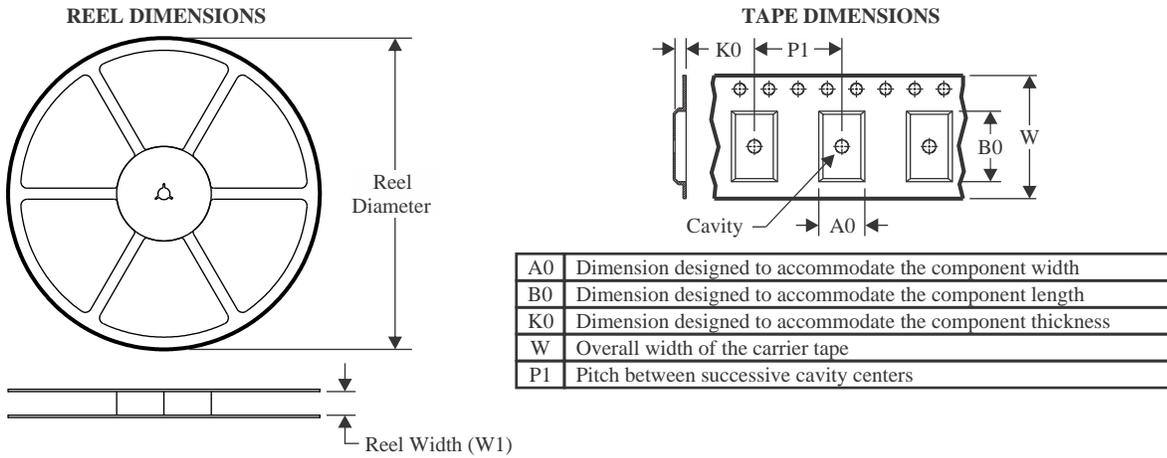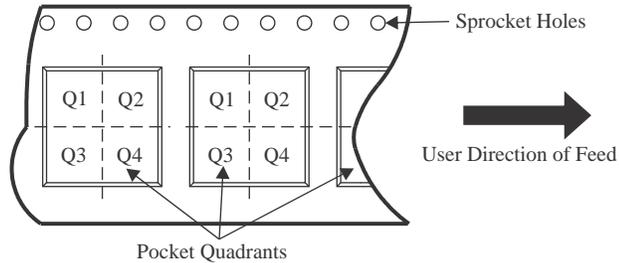
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF UC1842A-EP, UC1843A-EP, UC1844A-EP, UC1845A-EP :

- Catalog : UC1842A, UC1843A, UC1844A, UC1845A

- Space : UC1842A-SP, UC1843A-SP, UC1844A-SP, UC1845A-SP

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

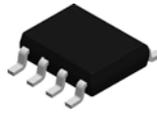**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC1842AMDREP	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UC1843AMDREP	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UC1844AMDREP	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UC1845AMDREP	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS
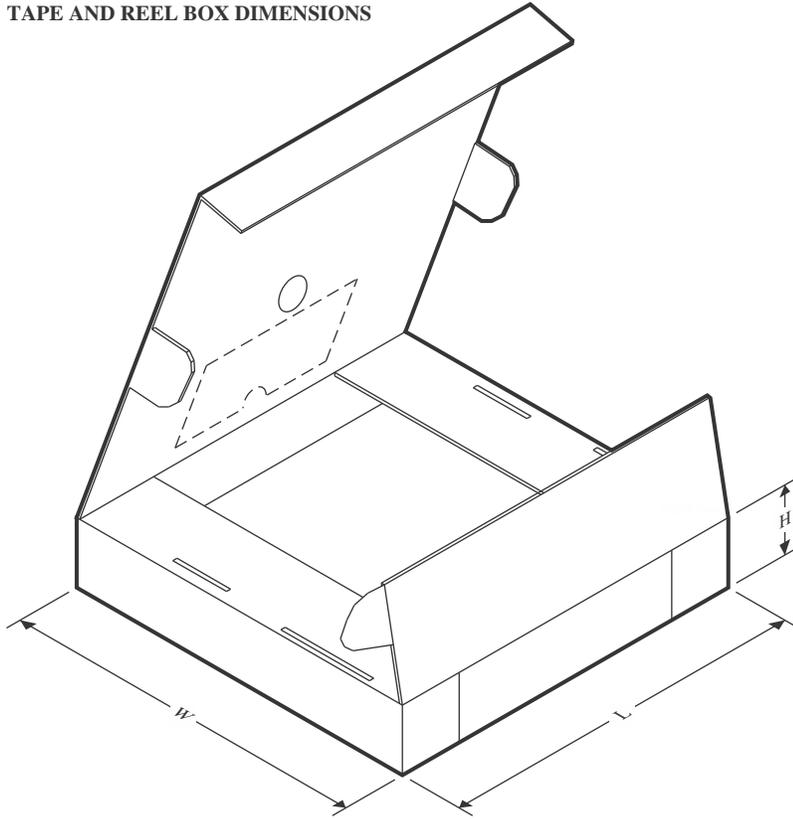
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UC1842AMDREP	SOIC	D	8	2500	350.0	350.0	43.0
UC1843AMDREP	SOIC	D	8	2500	350.0	350.0	43.0
UC1844AMDREP	SOIC	D	8	2500	350.0	350.0	43.0
UC1845AMDREP	SOIC	D	8	2500	350.0	350.0	43.0

.228-.244   TYP
[5.80-6.19]

PIN 1 ID AREA

A

1

8

6X .050
[1.27]

2X

.150
[3.81]

.189-.197
[4.81-5.00]
NOTE 3

4

5

B

.150-.157
[3.81-3.98]
NOTE 4

8X .012-.020
[0.31-0.51]

⊕ .010 [0.25] Ⓜ C A B

C

SEATING PLANE

⌒ .004 [0.1] C

4X (0°-15°)

.069 MAX
[1.75]

SEE DETAIL A

4X (0°-15°)

.005-.010   TYP
[0.13-0.25]

.010
[0.25]

0°- 8°

.016-.050
[0.41-1.27]

(.041)
[1.04]

.004-.010
[0.11-0.25]

DETAIL A
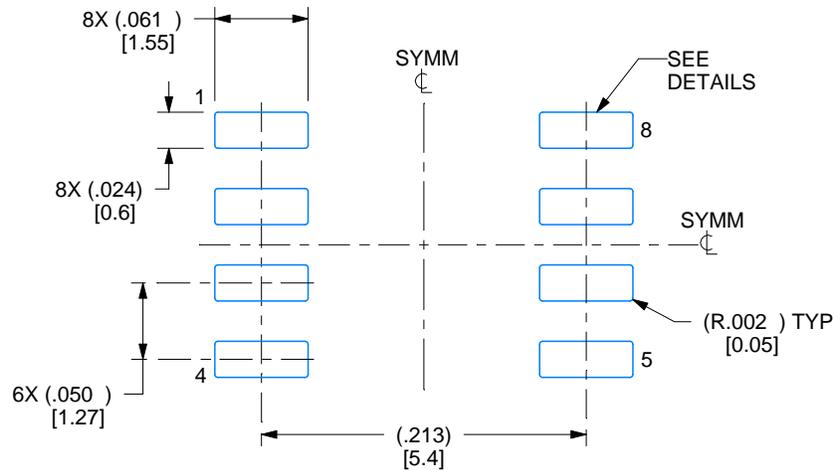TYPICAL
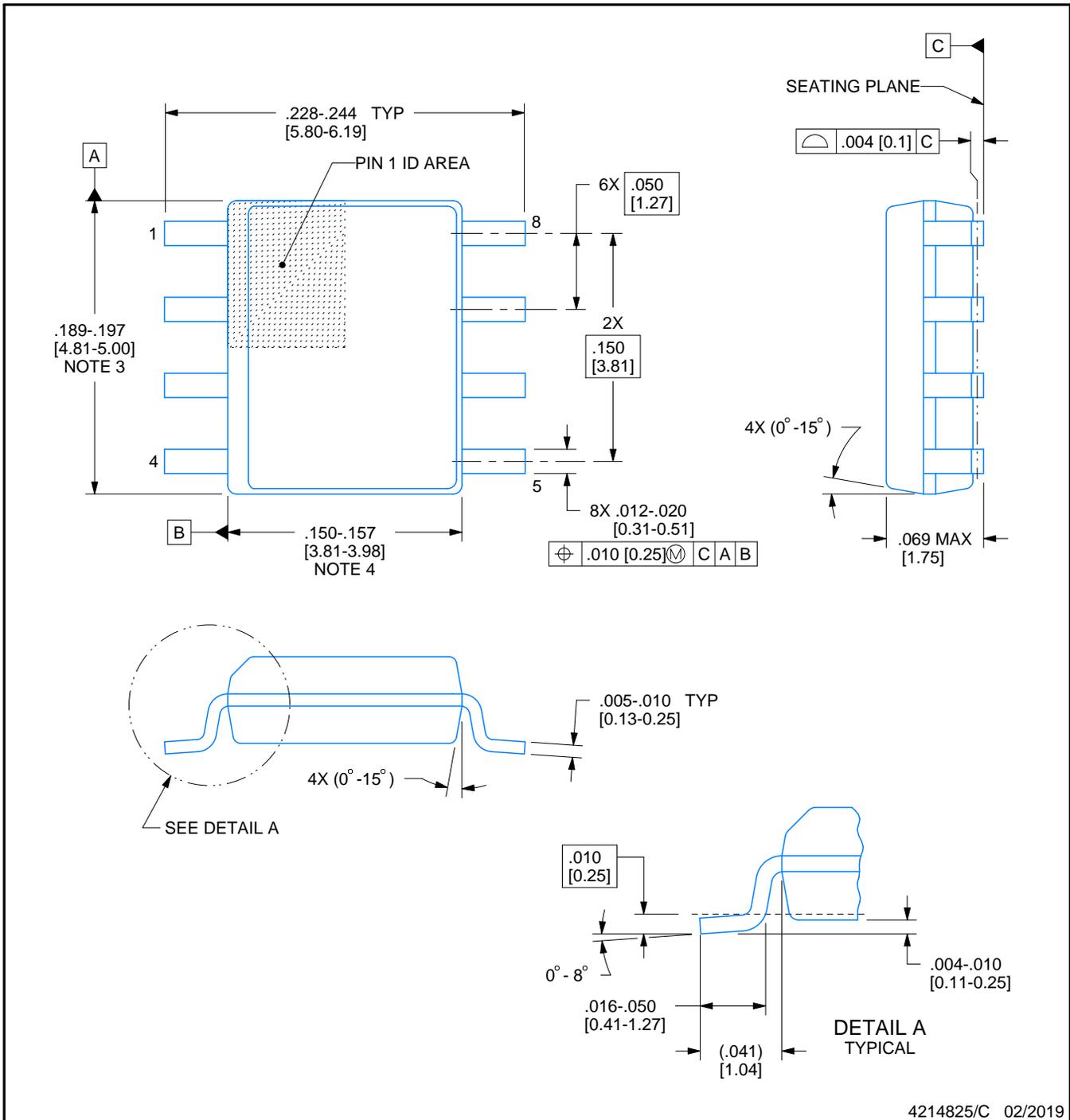
4214825/C   02/2019

NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches.
   Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
   exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

8X (.061)
[1.55]

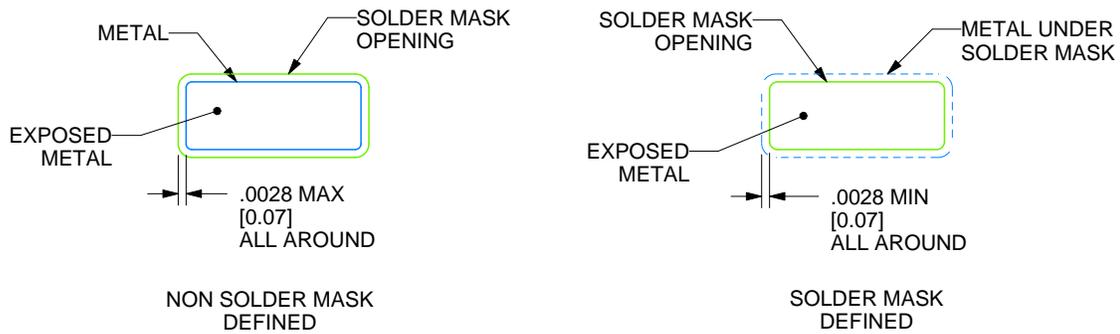SYMM
₵

SEE
DETAILS

1

8

8X (.024)
[0.6]

SYMM
₵

4

5

6X (.050)
[1.27]

(R.002) TYP
[0.05]

(.213)
[5.4]

LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X

METAL

SOLDER MASK
OPENING

SOLDER MASK
OPENING

METAL UNDER
SOLDER MASK

EXPOSED
METAL

EXPOSED
METAL

.0028 MAX
[0.07]
ALL AROUND

.0028 MIN
[0.07]
ALL AROUND

NON SOLDER MASK
DEFINED

SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)
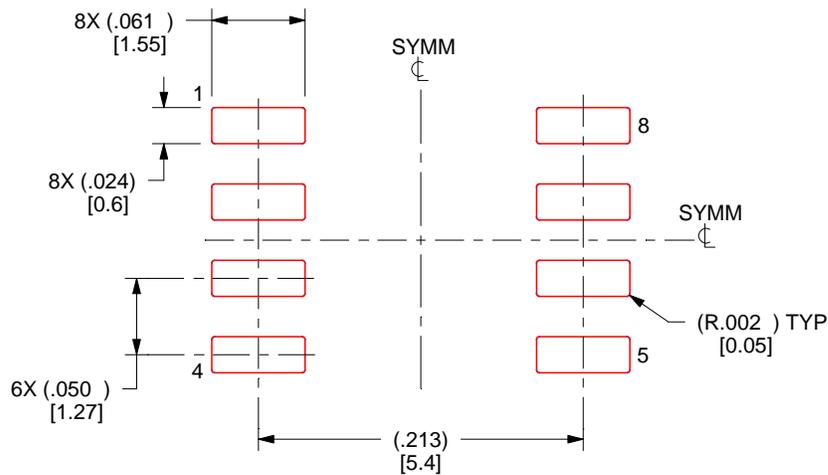
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

8X (.061)
[1.55]

SYMM

1

8X (.024)
[0.6]

SYMM

8

(R.002) TYP
[0.05]

6X (.050)
[1.27]

4

5

(.213)
[5.4]

SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C   02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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